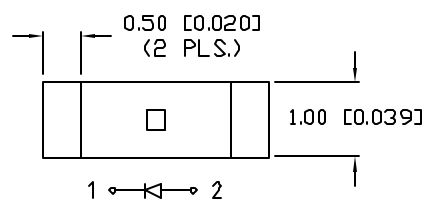


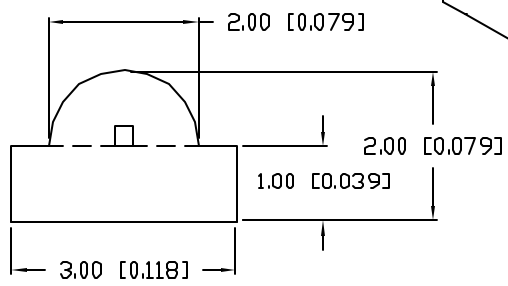
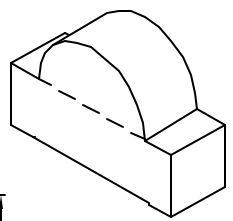
UNCONTROLLED DOCUMENT

PART NUMBER		REV.
SML-LXR851UPGC-TR		A

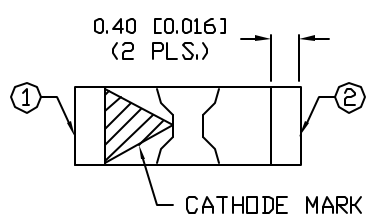
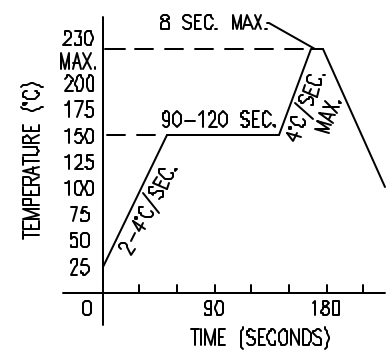
REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10967.	9.07.04



CAUTION: STATIC SENSITIVE DEVICE
 FOLLOW PROPER E.S.D. HANDLING PROCEDURES
 WHEN WORKING WITH THIS PART.



REFLOW PROFILE



ELECTRO-OPTICAL CHARACTERISTICS $T_A=25^{\circ}C$ $I_f=20mA$

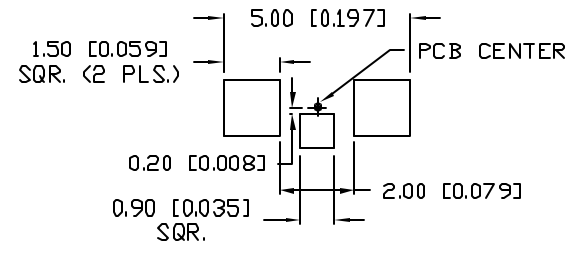
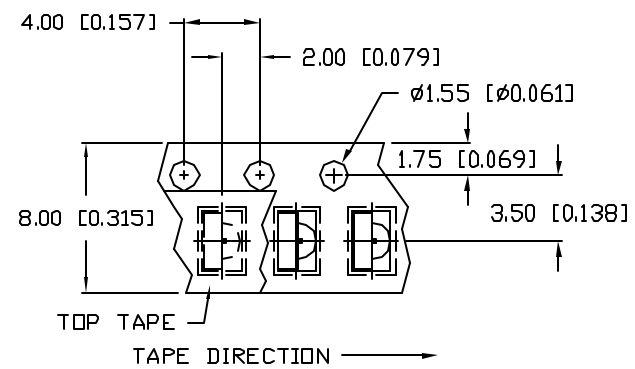
PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		525		nm	
FORWARD VOLTAGE		3.5	4.0	V_f	
REVERSE VOLTAGE	5.0			V_r	$I_f=100\mu A$
AXIAL INTENSITY		45		mcd	$I_f=20mA$
VIEWING ANGLE		160		2x theta	
EMITTED COLOR:	GREEN				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	160	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-25 TO +85	°C
STORAGE TEMP.	-30 TO +85	°C

* $t < 10\mu S$

RECOMMENDED PAD LAYOUT



CAUTION: MOISTURE SENSITIVE DEVICE
 PER JEDEC LEVEL 4 STANDARDS

NOTES:

- 2,000 PER REEL
- THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

UNCONTROLLED DOCUMENT

*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (+0.039), X.X=±0.5 (+0.020), X.XX=±0.25 (+0.010), X.XXX=±0.127 (+0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (+0.030), MIN.= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

REV.	PART NUMBER
A	SML-LXR851UPGC-TR

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1.0mm x 3.0mm PCB RIGHT ANGLE SURFACE MOUNT LED,
 525nm GREEN, WATER CLEAR LENS, 2K PER REEL.

RELIABILITY NOTE
 OUR MANY YEARS OF EXPERIENCE, DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:	CHECKED BY:	APPROVED BY:	DATE: 10.22.98
BC			PAGE: 1 OF 1
			SCALE: N/A